

# EPIGAP Optronic GmbH

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## Data Sheet

## Preliminary

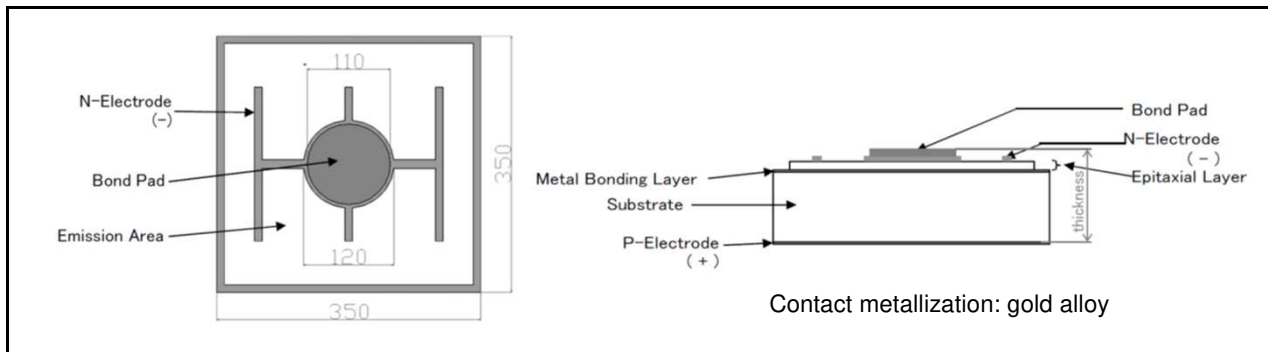
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## Infrared LED Chip

## EOLC-1200-27

Rev. 03, 2018

Radiation	Type	Electrodes
Infrared	InGaAs - based material, MQW	n (cathode) up



Die size (typ.): 0.350 mm × 0.350 mm (14 mil)

Thickness (typ.): 0.180 mm (7 mil)

Bond pad size: Ø 0.110 mm (periphery = Ø 0.120 mm)

### Optical and Electrical Characteristics

T<sub>amb</sub> = 25°C, unless otherwise specified

Parameter	Test cond.	Symbol	Min	Typ	Max	Unit
Forward voltage	I <sub>F</sub> =20 mA	V <sub>F</sub>		1.0		V
Radiant power*	I <sub>F</sub> =20 mA	Φ <sub>e</sub>		4.8		mW
Peak wavelength	I <sub>F</sub> =20 mA	λ <sub>p</sub>		1200		nm
FWHM	I <sub>F</sub> =20 mA	Δλ <sub>0.5</sub>		62		nm
Forward voltage	I <sub>F</sub> =50 mA	V <sub>F</sub>		1.1		V
Radiant power*	I <sub>F</sub> =50 mA	Φ <sub>e</sub>		9.6		mW
Forward voltage	I <sub>F</sub> =100 mA	V <sub>F</sub>		1.2		V
Radiant power*	I <sub>F</sub> =100 mA	Φ <sub>e</sub>		14.4		mW

\*Measured on bare chip on TO-18 header

### Packing

Dice on adhesive film with wire bond side up.



We reserve the right to make changes to improve technical design and may do so without further notice. Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer.

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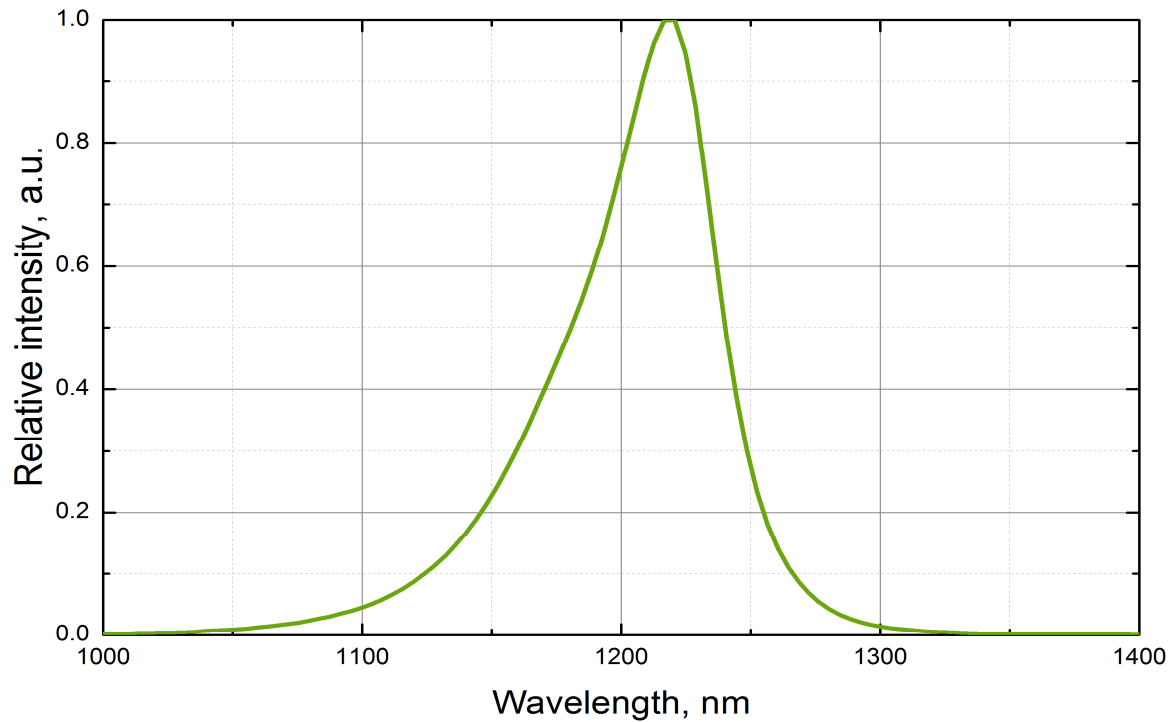
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Spectrum at 20 mA

Art. No. 113 165



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